🐺 Texas Instruments

## Bill of Materials

TI DESIGNS

## TIDA-00393

ltem	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part PCB Footprint	Note
1	2	C1, C2	4.7uF	Capacitor, Ceramic, 50V, X7R, 20%	STD	STD	1210	
2	1	C4	100nF	Capacitor, Ceramic, 50V, X7R, 20%	STD	STD	0603	
3	1	C5	10nF	Capacitor, Ceramic, 50V, X7R, 20%	STD	STD	0603	
4	1	C6	1nF	Capacitor, Ceramic, 50V, X7R, 20%	STD	STD	0603	
5	1	C7	47pF	Capacitor, Ceramic, 50V, X7R, 20%	STD	STD	0603	
6	1	C8	47uF	Capacitor, Ceramic, 6.3, X5R, 20%	TDK	C3216X5R0J476MT	1206	
7	1	C11	1 uF	Capacitor, Ceramic, 6.3, X5R, 20%	ТДК	STD	0603	
8	1	L1	6.8uH	Inductor, SMT, 3.84A, 35 mW	Sumida	CDRH103RNP-6R8	0.406 x 0.409	
9	1	SD1	B340A	Diode, Schottky, 3A, 40V	Diodes Inc	B340A	SMA	
10	1	SD2	1N4148	Diode Rectifier	Powerex Inc	1N4148	SMA	
11	1	R3	29.4kΩ	Resistor, Chip, 1/16W, 1%	STD	STD	0603	
12	1	R4	0Ω	Resistor, Chip, 1/16W, 1%	STD	STD	0603	
13	1	R5	499kΩ	Resistor, Chip, 1/16W, 1%	STD	STD	0603	
14	1	R6	150kΩ	Resistor, Chip, 1/16W, 1%	STD	STD	0603	
15	1	R7	1kΩ	Resistor, Chip, 1/16W, 1%	STD	STD	0603	
16	1	U2	TPS54331	IC, DC-DC Converter, 28V, 3A	ТІ	TPS54331D	SO-8	
17	1	U1	TPS70933	IC, 150 mA, ultra-low IQ, 1-μA LDO regul	a <sup>.</sup> TI	TPS70933DBV	SOT-23	

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